



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

EXAMINER: N. PAREKH )  
3 APPLICANT: PETER ELENIUS, ET AL. )  
4 SERIAL NO.: 09/575,298 )  
5 FILED: May 19, 2000 )  
6 FOR: "SOLDER BAR FOR HIGH POWER  
FLIP CHIPS" )  
7 )  
8 )  
9 )

Art Unit 2811

TECHNOLOGY CENTER 2800  
OCT 30 2002

RECEIVED

12/B  
11-23-02  
F Jones

Express Mail Mailing Label No. EL 816743855 US  
Date of Deposit: October 24, 2002

I hereby certify that this paper or fee is being deposited with  
the United States Postal Service "Express Mail Post Office to  
Addressee" service under 37 CFR §1.10 on the date indicated  
above and is addressed to BOX CPA, Commissioner for  
Patents, Washington, D.C. 20231.

  
Marvin A. Glazer

October 24, 2002  
Date

AMENDMENT

16 BOX CPA  
Honorable Commissioner for Patents  
17 Washington, D.C. 20231

18 Sir:

19 IN THE CLAIMS:

20 Please amend claim 16 as follows:

21 *Sub C* >  
22 ~~16. A reflowable solder bar formed upon an upper surface of a first substrate, the first  
23 substrate having a first electrical contact, said reflowable solder bar being adapted to join the  
24 first electrical contact to a second electrical contact on a second substrate, said reflowable  
25 solder bar comprising in combination:~~

26 a. a first generally circular solder pad formed upon the upper surface of the first  
27 substrate, the first generally circular solder pad having a center, and having a first  
28 predetermined diameter D;